ASSOCIATION CONNECTING	Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the encompass	substance es all low	s within the n er level mater	nanufactur rials for wh	er listed it hich the m	em. Note: anufacture	if the item is an as r has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Informa	ation														
Company name*	Company unique ID				Unique ID Authority					Response Date*					
onsemi										2025-05-12					
Contact Name	Title - Contact				Phone - Contact*					Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewar	rds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester	ster Item Number Mfr Item		n Number Mfr Item Name				Effective Dat	Date Version Manufacturing Site		ng Site	1	Veight*	UOM	Unit Type	
		NRVBAF360T3G Auto		Auto standard of MBRAF360T3G		2025-05-12					8	3.64	mg	Each	
Manufacturing P	Proccess Information	1		·											·
Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSL			L Rating	Peak Process Body Temperature Max Time at P			ne at Peak	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU A			CU Alloy	Alloy 1			260 C 30			seconds 3					
Comments															
evel 1 - maximum tir	me at peak temperature o	luring sol	dering is 10-3	0 seconds											
For more information	n regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	7.0	mg	Supplier	Zinc (Zn)	7440-66-6		0.0084	mg
			Supplier	Iron (Fe)	7439-89-6		0.1645	mg
			Supplier	Copper (Cu)	7440-50-8		6.825	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0021	mg
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	3.45	mg	Supplier	Silver (Ag)	7440-22-4		0.0862	mg
			А	Lead (Pb)	7439-92-1	7a	3.1913	mg
			Supplier	Tin (Sn)	7440-31-5		0.1725	mg
Lead Frame	28.84	mg	Supplier	Zinc (Zn)	7440-66-6		0.0346	mg
			Supplier	Iron (Fe)	7439-89-6		0.6777	mg
			Supplier	Copper (Cu)	7440-50-8		28.119	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0087	mg
Mold Compound-Black	41.85	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.185	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2092	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.0682	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27.2025	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.185	mg
Plating	1.38	mg	Supplier	Tin (Sn)	7440-31-5		1.38	mg